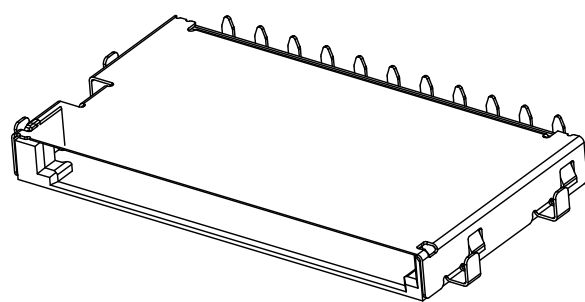


RECOMMEND P.C.B LAYOUT TOLERANCE ±0.05

- PAD
- No trace , no test point, no via hole, no ground area



- NOTES :**
- MATERIAL :**
    - HOUSING:LCP S475 UL94 V-0, BLACK COLOR.
    - SHELL:STAINLESS STEEL SUS304.
    - CONTACT:COPPER ALLOY C5210.
  - FINISH :**
    - CONTACT: GOLD PLATING ON CONTACT AREA, MATTE TIN 100u"MIN ON SOLDERTAIL AREA. 50u" MIN NICKEL PLATING OVERALL.
    - SHELL: 30u" MIN SOLDERABLE NICKEL PLATING OVERALL.

PART.NO.: SD29-AN401-\*\*

- 42: 功能区镀金1U",锡脚镀雾纯锡至少80U"
- 43: 功能区镀金3U",锡脚镀雾纯锡至少80U"
- 44: 功能区镀金5U",锡脚镀雾纯锡至少80U"
- 46: 功能区镀金15U",锡脚镀雾纯锡至少80U"
- 47: 功能区镀金30U",锡脚镀雾纯锡至少80U"

Pin Define		
Connector Pin No.	SD Card Pin No.	Pin Define
P1	P9	DAT2
P2	P1	DAT3
P3	P2	CMD
P4		CD
P5	P3	VSS1
P6	P4	VDD
P7	P5	CLK
P8	P6	VSS2
P9	P7	DAT0
P10	P8	DAT1
P11		W/P
P12~P15		GND

WITHOUT CARD		CARD INSERTED:LOCK		CARD INSERTED:UNLOCK	
W/P	GND	W/P	GND	W/P	GND
C/D	VSS1	C/D	VSS1	C/D	VSS1

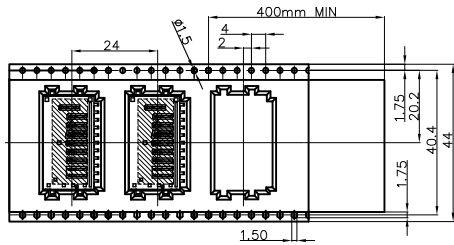
GENERAL TOLERANCE		DWG.NO.	SD29-AN401-00	PART.NO.	SD29-AN401-**	DRAWN	L.M.J 2016.04.19	UNIT	mm	SCALE	NO SCALE
x.±0.50	x. ± 5°	REV.	A	TITLE	SD+MMC NO Push 2.35 com	CHECKED		东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			
.x±0.25	.x ± 2°	SIZE		SHEET	1 OF 2	APPROVED					
.xx±0.15	.xx ± 1°	A4									

# 东莞市欧联电子科技有限公司

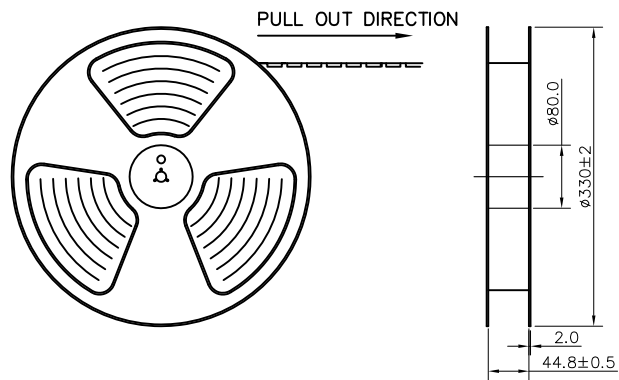
## 包装作业规范

### 包装作业图示及说明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

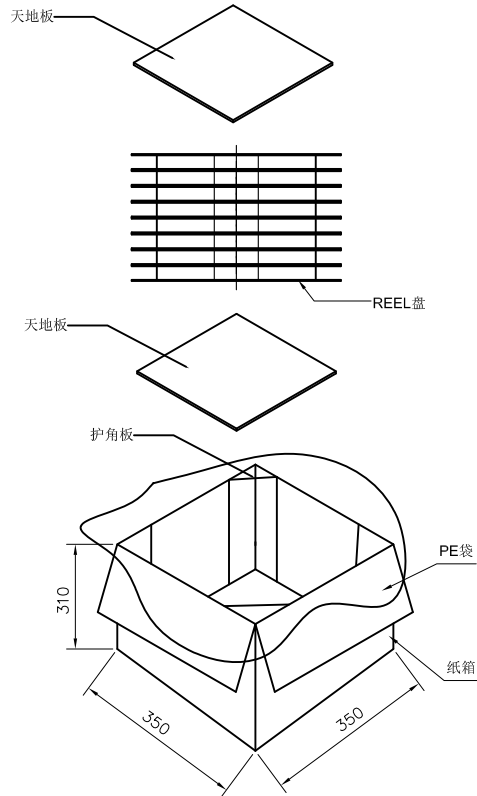
- 一.
- 1) 将成品一一放入REEL包装盘内,依同一方向放入.
  - 2) 包装时,如图所示.
  - 3) 一个REEL包装盘放置600个成品.



- 二.
- 1) 装盘前先把前面空10pcs产品,然后再开始装盘,尾端也需空17pcs产品.
  - 2) 装满成品的REEL包装盘如下图所示.



- 三.
- 1) 每箱装6盘REEL包装盘.
  - 2) 每箱放置3600PCS的成品.



- 四.
- 1) 用TAPE将纸箱封实.

#### 備註 (REMARK)

1. 若有未装满之零数箱,必须以缓冲材塞满.

GENERAL TOLERANCE		DWG.NO.	SD29-AN401-00	PART.NO.	SD29-AN401-**	DRAWN	L.M.J 2016.04.19	UNIT	mm	SCALE	NO SCALE
x.±0.50	x. ± 5°	REV.	A	TITLE	SD+MMC NO Push 2.35 com	CHECKED		<b>东莞市欧联电子科技有限公司</b> DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			
.x±0.25	.x ± 2°	SIZE		SHEET	2 OF 2	APPROVED					
.xx±0.15	.xx ± 1°	A4									